

In re: David B. Slater, Jr. et al.  
Application Serial No.: 10/659,241  
Filed: September 9, 2003  
Page 2 of 3

**In the Specification:**

Please amend the paragraph at Page 10, line 20-Page 11, line 2, as follows:

Referring now to Figure 2B, a phosphor-containing layer 220 is coated on the oblique sidewall 200d and also may be coated on the second face 200b. In some embodiments, the phosphor-containing layer may include a binder, such as an epoxy, a silicon-based matrix and/or other solvent. The phosphor may be cerium-doped YAG and/or other conventional phosphors. However, other conventional binders and/or phosphors may be used depending on the application. The phosphor may be coated on the LED by screen printing, evaporation (sputter, e-beam, thermal, CVD, electrostatic and/or ~~electrophoretic~~ electrophoretic deposition), dipping, spin coating and/or other techniques. The phosphor-containing layer 220 then may be cured at between about 50°C and about 200°C for about several seconds to several hours. The thickness of the phosphor-containing layer 220 may range between about 2µm and about 100µm, in some embodiments of the invention. However, other thicknesses may be used. The thickness that is used may be selected to reduce or minimize self-absorption and/or scattering and may depend on the coating process, the density of the phosphor and/or the desired application. Moreover, a coating process or combinations of coatings processes may be selected to control the thickness of the phosphor on the oblique sidewall 200d compared to the second face 200b.